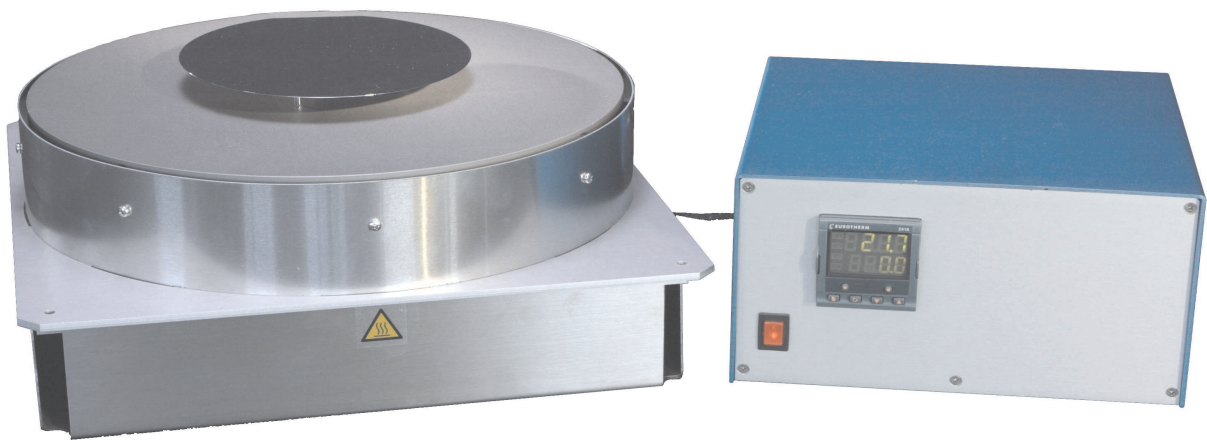


Model HPH-300

Hot chuck for up to 300 mm wafer size,
with part fixture by vacuum and (optional) lift pins

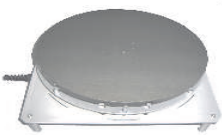




3 programmable process parameter:

- heat up rate
- lift pin up or down
- vacuum on or off

- for up to 300 mm (12") wafer size
- heated area: 306 mm diameter
- temperature up to 250 °C (continuous operation)
- high precision Eurotherm controller (model 2416)
- part fixture by vacuum; external vacuum pump required
- time controlled lift pins (free movement of the lift pins)
- USB interface for easy programming on PC, incl. software UniSoft

Technical Data HPH-300 Hot chuck

Model	HPH-300	HPH-300-L with lift pins
		
Heated area	306 mm diam.	306 mm diam.
Temperature range	ambient up to 250 °C	ambient up to 250 °C
Temperature distribution:	100 °C: ± 0.5 °C 200 °C: ± 1.5 °C	100 °C: ± 0.5 °C 200 °C: ± 2.5 °C
Lift pins	-	3 quartz lift pins; accepts 3" wafer up to 12" wafer size; various length of quartz pins on request
Vacuum hold	in the center of the chuck	in the center of the chuck
Dimensions hot chuck	330 x 330 x 130 mm	330 x 330 x 130 mm
Power supply	230 V/1600 W	230 V/1600 W
Weight	6 kg	6 kg
Controller	high precision Eurotherm PID controller (2416), resolution 0.1 °C	
Programming	1 program with 16 segments storable; programmable process steps: ramp up rate, lift pin up/down, vacuum hold on/off; incl. easy to use UniSoft software	
Interface	USB to PC	
Dimensions controller	220 x 220 x 125 mm	
Weight	3 kg	